L Number	Hits	Search Text	DB	Time stamp
1	38757	wiring near layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:17
2	133992	((contact conduct$3) near (via hole plug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:20
3	9363	(wiring near layer) and (((contact conduct$3) near (via hole plug)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:20
4	8109	((wiring near layer) and (((contact conduct$3) near (via hole plug)))) and (insulat$3 dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:21
5	4080	(((wiring near layer) and (((contact conduct$3) near (via hole plug)))) and (insulat$3 dielectric)) and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:21
6	3939	((((wiring near layer) and (((contact conduct$3) near (via hole plug)))) and (insulat$3 dielectric)) and gate) and (substrate base)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:23
7	2852	(((((wiring near layer) and (((contact conduct$3) near (via hole plug)))) and (insulat$3 dielectric)) and gate) and (substrate base)) and (source and drain)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:25
8	1802	((((((wiring near layer) and (((contact conduct$3) near (via hole plug)))) and (insulat$3 dielectric)) and gate) and (substrate base)) and (source and drain)) and (gate near insulat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 10:25